

Applicant:	Yi Yeol LYU et al.	Conf.:	4059
Appl. No.:	10/621,380	Group:	1712
Filed:	July 18, 2003	Examiner:	M. G. MOORE
For:	SILOXANE-BASED RESIN AND METHOD FOR FORMING INSULATING FILM BETWEEN INTERCONNECT LAYERS IN SEMICONDUCTOR DEVICES BY USING THE SAME		

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith is a response to notice of non-compliant amendment in the above-identified application.

- ☐ The enclosed document is being transmitted via the Certificate of Mailing provisions of 37 C.F.R. § 1.8.
- ☐ The enclosed document is being transmitted via facsimile.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT					HIGHEST NUMBER PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	12	-	20	=	0		\$50	\$0.00	
INDEPENDENT	2	-	3	=	0		\$200	\$0.00	
<input type="checkbox"/> FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM							\$360	\$0.00	
							TOTAL	\$0.00	

- ☐ Petition for () month(s) extension of time pursuant to 37 C.F.R. §§ 1.17 and 1.136(a). \$0.00 for the extension of time.
- ☒ No fee is required.
- ☐ Check(s) in the amount of \$0.00 is(are) enclosed.
- ☐ Please charge Deposit Account No. 02-2448 in the amount of \$0.00. This form is submitted in triplicate.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees.

Respectfully submitted,

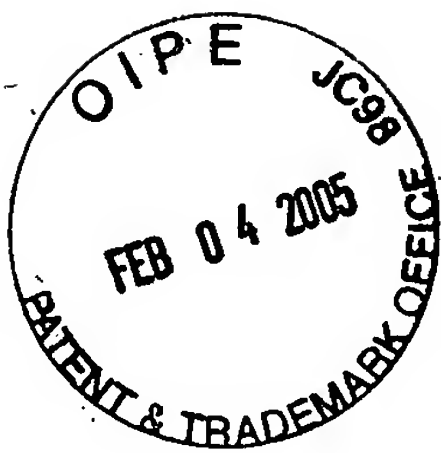
BIRCH, STEWART, KOLASCH & BIRCH, LLP

By Robert E. Guernsey #42,593
for Joseph A. Kolasch, #22,463

JAK/REG:jls
3811-0122P

P.O. Box 747
Falls Church, VA 22040-0747
(703) 205-8000

Attachment(s)



PATENT
3811-0122P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:	Yi Yeol Lyu et al.	Conf.:	4059
Appl. No.:	10/621,380	Group:	1712
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For:	SILOXANE-BASED RESIN AND METHOD FOR FORMING INSULATING FILM BETWEEN INTERCONNECT LAYERS IN SEMICONDUCTOR DEVICES BY USING THE SAME		

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

February 4, 2005

Sir:

In reply to the Notice of Non-Complaint Amendment mailed January 28, 2005, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes a substitute claim set and remarks.